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BONDPAD ATTACHMENTS USED TO TEMPORARILY
CONNECT SEMICONDUCTOR DIE

ABSTRACT

5 A die contacting substrate establishes ohmic contact with
the die by means of raised portions on contact members. The
raised portions are dimensioned so that a compression force
applied to the die against the substrate results in a limited
penetration of the contact member into the bondpads. The
arrangement may be used for establishing electrical contact
10 ~~and~~ with a burn-in oven and with a discrete die tester. This
permits the die to be characterized prior to assembly, so that
the die may then be transferred in an unpackaged form. A
Z-axis anisotropic conductive interconnect material may be
interposed between the die attachment surface and the die.

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